

# SOT1954-1

FBGA352, plastic fine-pitch ball grid array package, 352 balls,  
0.8 mm pitch, 17 mm x 17 mm x 1.63 mm body

13 December 2017

Package information

## 1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	FBAG352
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	28-11-2017
Manufacturer package code	98ASA01144D

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		-	-	17	-	mm
E	package width		-	-	17	-	mm
A <sub>2</sub>	package height		-	-	1.63	-	mm
e	nominal pitch		-	-	0.8	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	352	-	A/A



2. Package outline

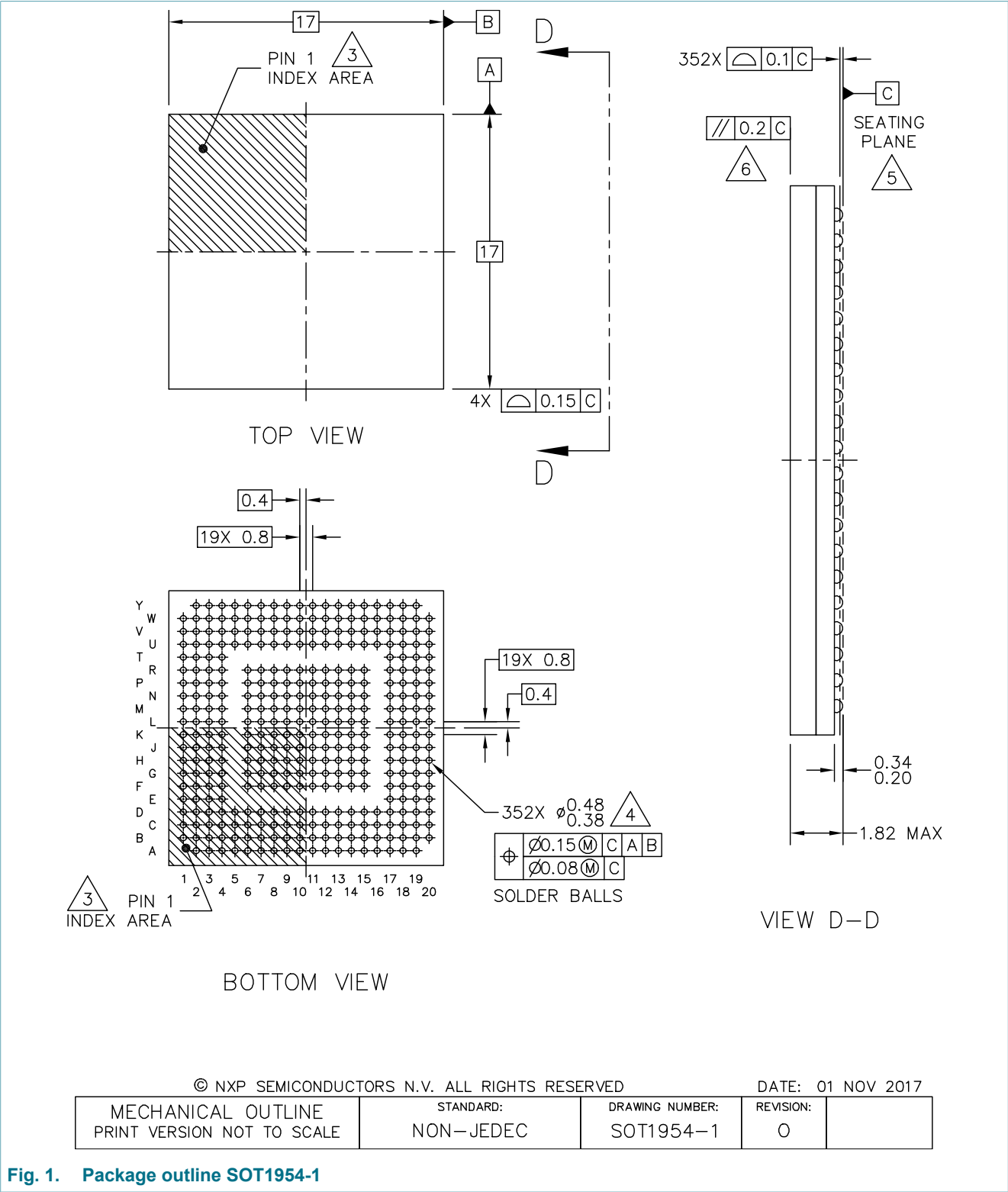


Fig. 1. Package outline SOT1954-1

- NOTES:
1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3.

PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4.

MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.

5.

DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6.

PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON–JEDEC	DRAWING NUMBER: SOT1954–1	REVISION: O	

**Fig. 2. Package outline note FBGA352 (SOT1954-1)**

### 3. Legal information

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